30 V, 2 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e²PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	-30	Vdc
Collector-Base Voltage	V_{CBO}	-50	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ic	-1.0	Α
Collector Current - Peak	I _{CM}	-2.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit		
Total Device Dissipation T _A = 25°C	P _D (Note 1)	310	mW		
Derate above 25°C		2.5	mW/°C		
Thermal Resistance, Junction to Ambient	R _{0JA} (Note 1)	403	°C/W		
Total Device Dissipation T _A = 25°C	P _D (Note 2)	710	mW		
Derate above 25°C		5.7	mW/°C		
Thermal Resistance, Junction to Ambient	R _{θJA} (Note 2)	176	°C/W		
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	575	mW		
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

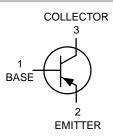
- 1. FR-4 @ Minimum Pad.
- 2. FR-4 @ 1.0 X 1.0 inch Pad.
- 3. Refer to Figure 8.



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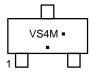
$\begin{array}{c} 30 \text{ VOLTS} \\ 2.0 \text{ AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 200 m} \Omega \end{array}$





SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



VS4 = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]		
NSS30100LT1G, NSV30100LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

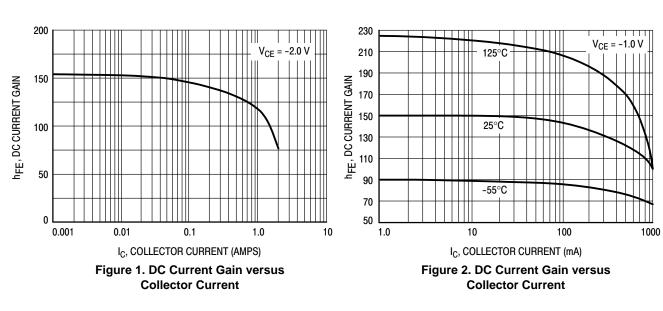
$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_A = 25^{\circ}\text{C unless otherwise noted})$

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-30	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	-50	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	-5.0	_	Vdc
Collector Cutoff Current (V _{CB} = -30 Vdc, I _E = 0)	I _{CBO}	_	-0.1	μAdc
Collector–Emitter Cutoff Current (V _{CES} = -30 Vdc)	I _{CES}	_	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -4.0 Vdc)	I _{EBO}	_	-0.1	μAdc
ON CHARACTERISTICS				
DC Current Gain (Note 4) (Figure 1) $ (I_C = -1.0 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = 2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h _{FE}	100 100 80 40	- 300 - -	
Collector – Emitter Saturation Voltage (Note 4) (Figure 3) $ \begin{array}{l} (I_C=-0.5~A,~I_B=-0.05~A) \\ (I_C=-1.0~A,~I_B=0.1~A) \\ (I_C=-2.0~A,~I_B=-0.2~A) \end{array} $	V _{CE(sat)}	- - -	-0.25 -0.30 -0.65	V
Base – Emitter Saturation Voltage (Note 4) (Figure 2) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V _{BE(sat)}	_	-1.2	V
Base – Emitter Turn–on Voltage (Note 4) $(I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V})$	V _{BE(on)}	-	-1.1	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	100	-	MHz
Output Capacitance (f = 1.0 MHz)	Cobo	-	15	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS



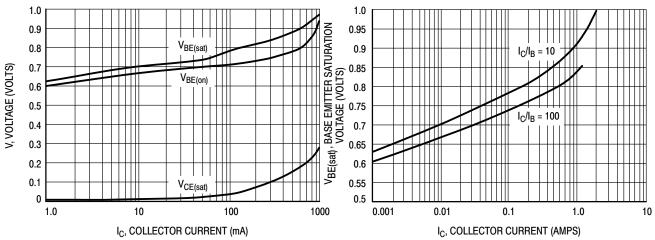


Figure 3. "On" Voltages

Figure 4. Base Emitter Saturation Voltage versus Collector Current

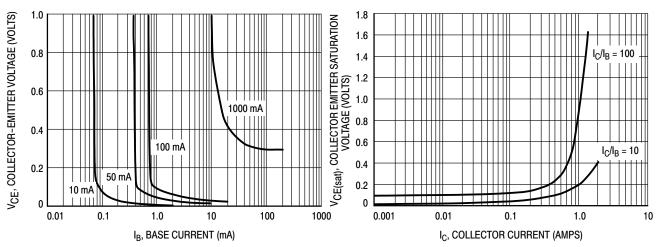


Figure 5. Collector Emitter Saturation Voltage versus Base Current

Figure 6. Collector Emitter Saturation Voltage versus Collector Current

TYPICAL CHARACTERISTICS

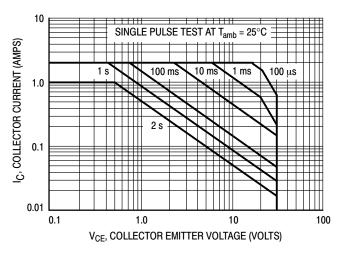


Figure 7. Safe Operating Area

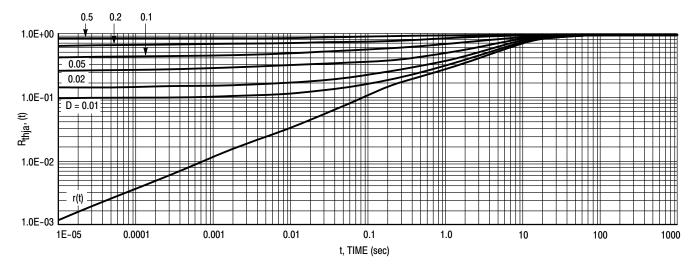
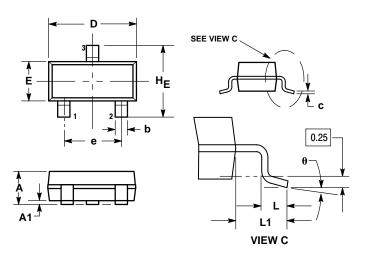


Figure 8. Normalized Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AP**



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS.

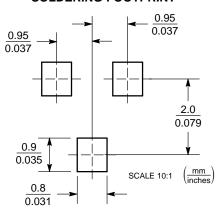
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 6:

PIN 1. BASE

- **EMITTER**
- COLLECTOR

SOLDERING FOOTPRINT



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